

INTERNATIONAL STANDARD

IEC 61249-3-5

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Materials for printed boards and other interconnecting structures –

Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) – Transfer adhesive films

*Matériaux pour circuits imprimés et autres structures
d'interconnexion –*

*Partie 3-5:
Collection de spécifications intermédiaires pour les matériaux
de base non renforcés, recouverts ou non
(prévus pour les circuits imprimés flexibles)
Films à transfert de colle*

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MATERIALS FOR PRINTED BOARDS
AND OTHER INTERCONNECTING STRUCTURES –**

**Part 3-5: Sectional specification set for unreinforced base materials,
clad and unclad (intended for flexible printed boards) –
Transfer adhesive films**

FOREWORD

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International Standard IEC 61249-3-5 has been prepared by IEC technical committee 52: Printed circuits.

The text of this standard is based on the following documents:

FDIS	Report on voting
52/774/FDIS	52/799/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

Annex A is for information only.

A bilingual version of this standard may be issued at a later date.

MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) – Transfer adhesive films

1 Scope

This part of IEC 61249 gives requirements for transfer adhesive films for use in the fabrication of flexible multilayer boards or flex-rigid printed boards.

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 61249. At the time of publication, the editions indicated were valid. All normative documents are subject to revision, and parties to agreements based on this part of IEC 61249 are encouraged to investigate the possibility of applying the most recent editions of the normative documents listed below. Members of IEC and ISO maintain registers of currently valid International standards.

IEC 60249-1:1982, *Base materials for printed circuits – Part 1: Test methods*

IEC 60249-2-8:1987, *Base materials for printed circuits – Part 2: Specifications – Specification No. 8: Flexible copper-clad polyester (PETP) film*

IEC 60249-2-13:1987, *Base materials for printed circuits – Part 2: Specifications – Specification No. 13: Flexible copper-clad polyimide film, general purpose grade*

IEC 60249-2-15:1987, *Base materials for printed circuits – Part 2: Specifications – Specification No. 15: Flexible copper-clad polyimide film of defined flammability*

IEC 61189-2:1997, *Test methods for electrical material interconnection structures and assemblies – Part 2: Test methods for materials for interconnection structures*